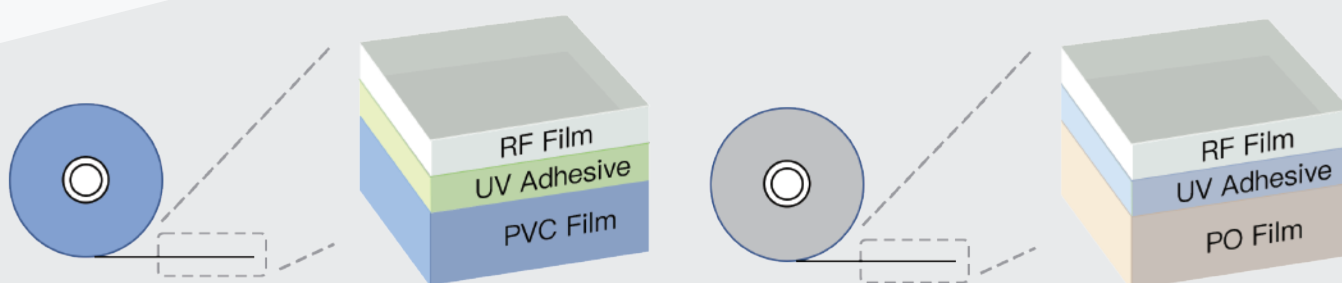
GTA
Material Co.,Ltd.

晶圓切割膠帶 Wafer Dicing Tape

適用於晶圓切割製程的壓克力PO膠帶與壓克力PVC膠帶，使用高模量的黏膠，在切割過程中對晶圓提供強而有力的支撐，避免切割時邊緣出現碎裂或毛邊。於室溫環境下展現穩定的黏著特性，膠帶對UV光敏感，在 LED 365nm 曝光後附著力降低，可輕鬆去除膠帶，且膠體延伸性佳，不會殘膠。

結構 / Structure



特性 / Features

- 具有優異的延伸性能，在膠帶撕除過程中不會在基材上留下殘膠。
- 黏著特性於室溫環境穩定，365nm紫外光解黏型，照射後附著力降低。
- 採用高模量設計，黏膠在切割時牢固貼合晶片，避免切割邊緣碎裂或毛邊。

規格 / Specification

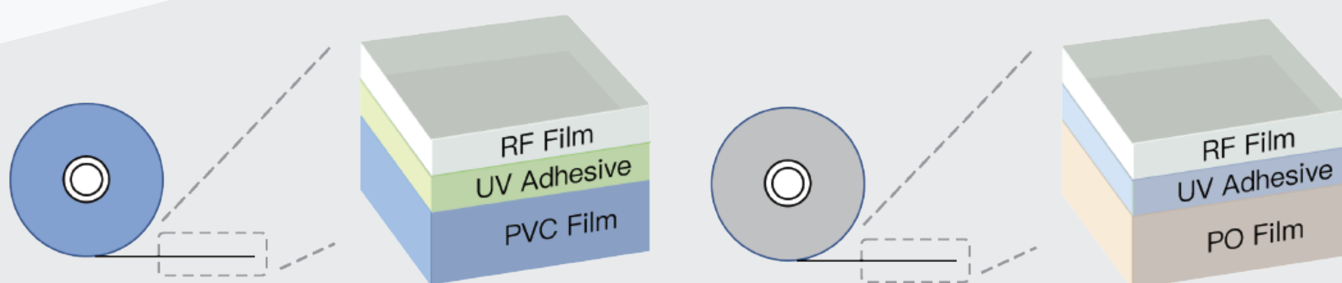
產品名稱		UC090	UO110-ST	UO110-HT
膠帶厚度		90	110	110
膠黏層厚度		10	10	10
黏著力 (gf/25mm)	紫外線曝前	180	200	350
	紫外線曝後	30	10	20
抗拉強度 (kg/cm^2)	MD	230	280	410
	TD	220	230	380
基材		PVC	PO	PO

GTA Material Co., Ltd.
+886-2-3234-0086 www.gta.com.tw

Wafer Dicing Tape

The acrylic PO tape and PVC tape is suitable for application in wafer dicing process. The high modulus adhesive strongly support wafer in the dicing process and avoid chipping or burrs on cut edges. The adhesive layer shows stable adhesion at ambient condition, sensitive to UV-light, easily removable after exposure of 365nm LED without leaving adhesive residue.

Structure



Features

- Stable adhesion force and reduced adhesion after 365nm UV exposure.
- With high modulus design, the adhesive strongly wafer in dicing and avoid chipping or burrs on cut edges.
- With excellent elongation performance, no adhesive residue would stay on substrate in the tape tear-off process.

Specification

Product name		UC090	UO110-ST	UO110-HT
Tape thickness		90	110	110
Adhesive thickness		10	10	10
180° peel force (gf/25mm)	Before UV	180	200	350
	After UV	30	10	20
Tensile strength (kg/cm^2)	MD	230	280	410
	TD	220	230	380
Base film		PVC	PO	PO

GTA Material Co., Ltd.
+886–2–3234–0086 www.gta.com.tw